

LISTING OF CLAIMS:

The following listing of claims replaces all previous versions and listings of claims in the present application.

1. (Currently amended) A composite integrated circuit device comprising:

a lead frame;

a substrate whose bottom surface is attached with an adhesive over a top surface of a seat member of the lead frame;

a heater element that generates heat while running and is mounted on a first area of the top surface of the substrate; and

a temperature-restricted element that has restriction in operating temperature and is mounted on a second area of the top surface of the substrate,

wherein the lead frame and the substrate are molded with a mold resin,

wherein the seat member of the lead frame includes a hollow member that corresponds to a given area of the top surface of the substrate, and

wherein the given area includes at least a portion of an intermediate area that is located between the first area and the second area while the given area excludes the second area, and

wherein the hollow area is formed as a cut portion penetrating the seat member of the lead frame.

2. (Withdrawn) The composite integrated circuit device according to Claim 1,

wherein the seat member of the lead frame is thicker than a lead pin that is formed from the lead frame, and

wherein the bottom surface of the seat member is exposed without the mold resin.

3. (Original) The composite integrated circuit device according to Claim 1,

wherein the given area is formed as being surrounding the first area.

4. (Original) The composite integrated circuit device according to Claim 3,

wherein the given area includes the first area.

5. (Original) The composite integrated circuit device according to Claim 3,

wherein the given area is formed as being furthermore surrounding the intermediate area.

6. (Withdrawn) The composite integrated circuit device according to Claim 1,

wherein the given area is formed as being surrounding the second area.

7. (Withdrawn) The composite integrated circuit device according to Claim 6,

wherein the given area includes the second area.

8. (Withdrawn) The composite integrated circuit device according to Claim 6,

wherein the given area is formed as being furthermore surrounding the intermediate area.

9. (Original) The composite integrated circuit device according to Claim 1,

wherein the hollow member is formed through cutting of press work.

10. (Withdrawn) The composite integrated circuit device according to Claim 1,

wherein the hollow member is formed through cutting of press work, and

wherein the first area and the second area are separated from each other by the hollow member.

11. (Withdrawn) The composite integrated circuit device according to Claim 1,

wherein the hollow member is formed as a concave portion through press work.

12. (Withdrawn) The composite integrated circuit device according to Claim 11,

wherein the concave portion remains as a cavity.

13. (Withdrawn) The composite integrated circuit device according to Claim 11,

wherein the concave portion is filled with one of the adhesive and the mold resin.

14. (Withdrawn) The composite integrated circuit device according to Claim 11,

wherein the concave portion is formed in the top surface of the seat member.

15. (Original) The composite integrated circuit device according to Claim 1,

wherein the given area is larger than at least one of the first area and the second area.